

AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0024] as follows.

[0024] Wafer 120 is predominantly made of silicon and/or other materials that are transparent to the wavelength (e.g., 1100 nm or longer) of the optical signals from lasers 110. Wafer 120 also includes circuit elements such as bonding pads 122, ~~and~~ electrical traces 170, or vias (not shown) that connect lasers 110 to external terminals 124. In the illustrated embodiment, external terminals 124 are on the top surface of sub-mount wafer 120, but the external terminals could alternatively be provided on the bottom surface. Additionally, active devices (not shown) such as transistors, an amplifier, or a monitor/sensor can be incorporated in wafer 120.